

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	ZK.CHEN	03/09'07
B	ECN-C070107-1/3 <input checked="" type="checkbox"/> CHANGE D/C	Charlie Gui	05/22'07

NOTE:

1. MATERIAL:

HOUSING:HIGH THERMAL PLASTIC. W/30% GF.,UL94V-0,COLOR BLACK.

CONTACT A&CONTACT B:COPPER ALLOY,T=0.10;

2. FINISH:

CONTACT A&CONTACT B:

30u" MIN GOLD PLATING ON CONTACT AREA;

1u" MIN GOLD PLATING ON SOLDERTAILS;

50u"~180u" MIN NICKEL UNDERPLATING OVERALL.

3. SPECIFICATION:SEE 2.54mm PITCH SIM CARD SMT TYPE PRODUCT SPEC.

4. SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10SEC.

5. TO CONFORM TO THE "SE-01-001" & "ROHS DIRECTIVE".

6. GREEN PRODUCT IDENTIFICATION IN PACKING: **G.P. PASS**

7. FOR REFLOW SOLDERING LEED FREE PROCESS.

8. P/N DESCRIPTION:

2SM2000-003011

PACKAGE:TAPE AND REEL

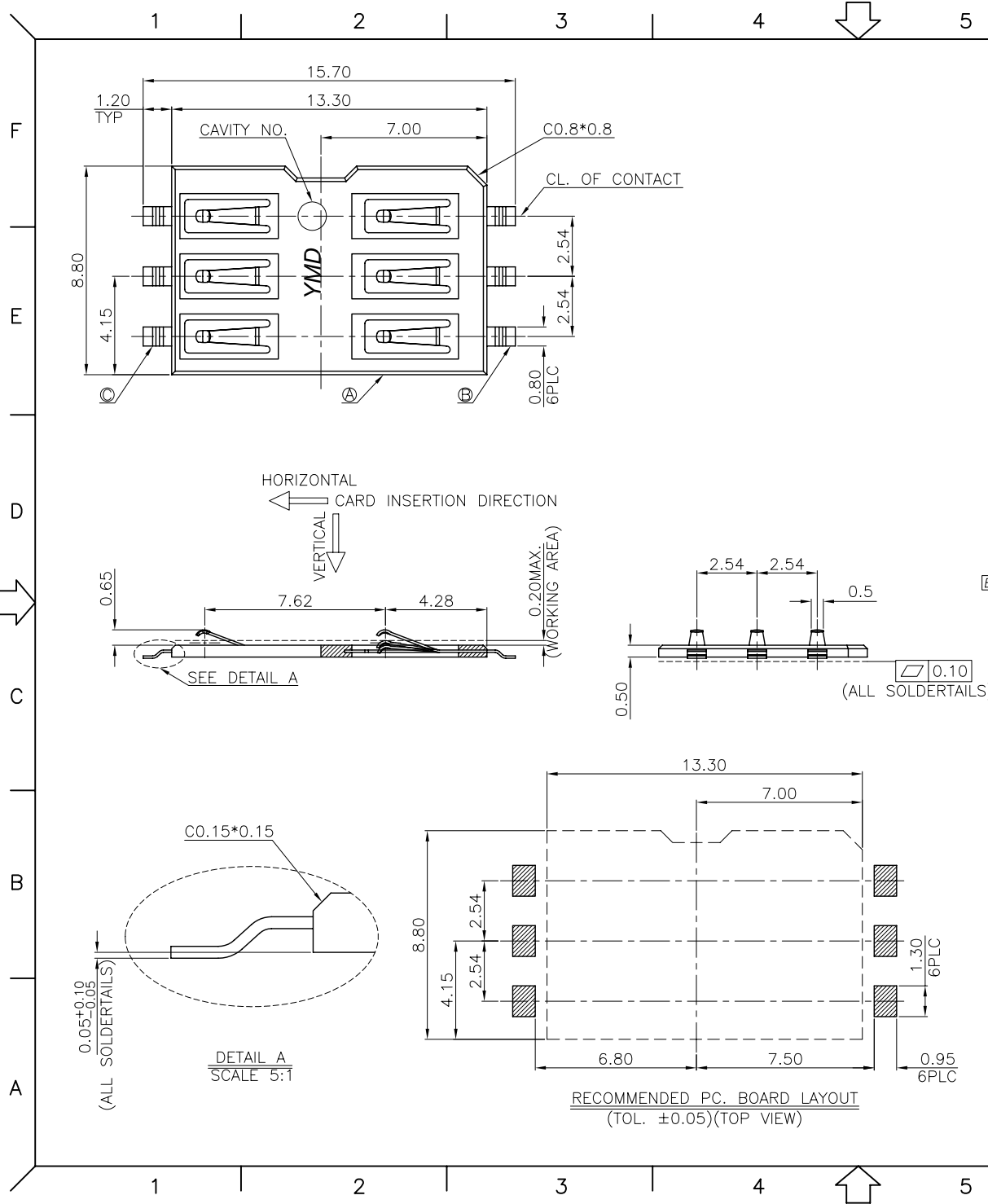
HOUSING COLOR:BLACK

CONTACT FINISH:GOLD 30u" MIN ON CONTACT AREA

NOTCH:WITH NOTCHES IN SIDE AND CORNER OF HOUSING

9. D/C DESCRIPTION:

Y M D  
DAY  
MONTH  
YEAR



C	CONTACT B	3	COPPER ALLOY,0.10T	SEE NOTES
B	CONTACT A	3	COPPER ALLOY,0.10T	SEE NOTES
A	HOUSING	1	HI-THERMAL PLASTIC,UL94V-0	COLOR BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING&COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES			Singatron Electronic(Chung-Shan) Co., Ltd. 	
DECIMALS:		ANGLES:	TITEL 2.54mm PITCH SIM CARD 6P 0.5H SMT TYPE	
X	:±0.5	X	:±2°	DWN Charlie Gui 05/22'07 PART NO. 2SM2000-003011
X.X	:±0.3	X.X	:±1°	CHKD ZK CHEN 05/22'07 SCALE: N/A UNIT: mm
X.XX	:±0.2			APVD SEAN LONG 05/22'07 SIZE: A3 SHEET: 10F1 REV: B
CUSTOMER COPY				